	CONNECTING CS INDUSTRIES® international and Pan	PC, Bannockb	ourn, Illinois. A	All rights reserved untions.	under both	This docume level parts, t	ent is a declaration	tion of the encomp	he substances asses all low	within the er level ma	manufactur terials for wl	er listed ite hich the m	em. Note: if anufacturer	the item is an as has engineering	ssembly with low responsibility.	
752-21.1					Form Type Distribute	 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater 					eous Materia	ials and Mfg Information				
upplie	r Information															
ompany	name*	Company unique ID			1	Unique ID Authority					Response Date*					
nsemi											2024-05-03					
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*						
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*						
roduct-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	e Vers	Version Manufacturing Site		ring Site	v	Veight*	UOM	Unit Type	
		NTHL099N60S5 Sup		SuperFET5 EASY, 99mohm, TO-247-3		2024-05-03 CI		СРА		5	456.925	mg	Each			
Ianufa	cturing Proccess Informat	tion							I							
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		J-STD-020 MSI	L Rating	Peak Process Body Temperat		ure Max Time at Peak Temp		Temperatu	ire Numb	er of Reflow Cyc	cles		
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		second	ls 3					
omments	3															
or more	information regarding material	composition	please refer to	o page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon (Si)	7440-21-3		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			А	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
Lead Frame	3612.9	mg	Supplier	Iron (Fe)	7439-89-6		3.6129	mg
			Supplier	Copper (Cu)	7440-50-8		3608.2031	mg
			Supplier	Phosphorus (P)	7723-14-0		1.0839	mg
Mold Compound-Black	-Black 1740.0	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		87	mg
			Supplier	Proprietary	Proprietary Data		87	mg
			Supplier	Carbon Black (C)	1333-86-4		8.7	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		78.3	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1305	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		87	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		87	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg